

Product Document



Premstaetten, January 14, 2021

PCN04A-2020 – Test Location and Test Platform Change for CMV12000 Mono

Dear Customer,

Please be informed about the upcoming test location change to ams qualified subcontractor KYEC located in Taiwan and test platform change of ams CMV12000 product family.

Change Description

For the CMV12000 family, ams is currently using proprietary testers developed and built inhouse. ams will transfer both the wafer probing as well as the final electrical test for the concerned products to the Teradyne IP750EX ATE test platform. Both tests will be done at the qualified test subcontractor KYEC, whereas now wafer probing is done at ams and final electrical test is done at the assembly subcontractor.

Traceability

The ams ERP system assures the traceability by batch ID.

Implementation Date and Schedule

ams AG intends to release the transfer of the wafer probing as well as the final electrical test for the below products to the Teradyne IP750EX ATE test platform in Q1/2021.

Affected part number list:

Material Part Number	Material Description
302010010	CMV12000HDR-2E5M1PA QA



Impact on Product

No change in form, fit or function.

Process Flow	Current Site	New Site
Wafer Fabrication	TowerJazz	TowerJazz
Sort	ams Sensors Belgium @ Proprietary Test System	KYEC @ Teradyne IP750EX
Assembly	Kanematsu Futuretech	Kanematsu Futuretech
Final Test	Kanematsu Futuretech @ Proprietary Test System	KYEC @ Teradyne IP750EX
Delivery	ams Sensors Belgium	ams Sensors Belgium

Please be advised that unless ams receive your written refusal concerning this change notification within 30 days, the change notification shall be deemed accepted.

If you do have further questions, please do not hesitate to contact ams at any time.

Best regards,

Peter Crabbe
ams AG
Director Operations CIS